

MS-V088 VER 0A

NV43-PCIE NV43 256MB/128bit, BGA 16MX16 DDR2,VGA,DVI-I,TV-OUT(HT-10)

P295-A00 DESIGN NV43 300/267MHZ 128MB/256MB/512MB DDR2 84-FBGA

PAGE SUMMARY: **DDR2 84-FBGA Clock setting 350MHZ**

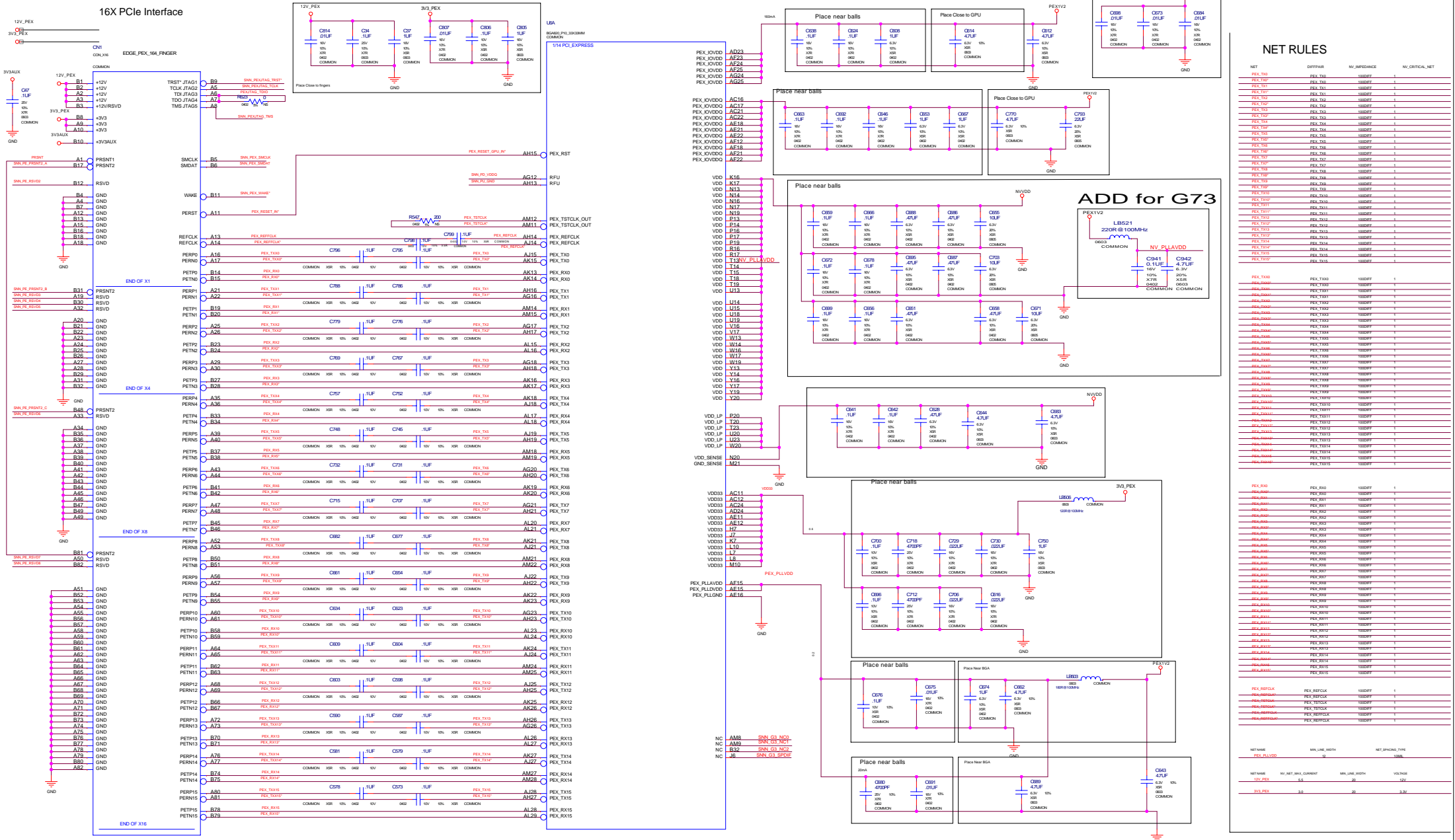
- Page1: P295 Overview
- Page2: PCI EXPRESS, NVVDD, VDD33
- Page3: FB BANK A, FBVTT TERMINATIONS, FBVDDQ DECOUPLING
- Page4: FB BANK C, FBVTT TERMINATIONS
- Page5: MEMORY PARTITION A 0..31
- Page6: MEMORY PARTITION A 32..63
- Page7: MEMORY PARTITION C 0..31
- Page8: MEMORY PARTITION C 32..63
- Page9: GPU GND
- Page10: DACA - VGA
- Page11: DACB - TVOUT, VIDEO IN
- Page12: DACC - VGA
- Page13: STRAPS, FANSINK, MECHANICALS
- Page14: GPIO, HDCP ROM, VBIOS ROM, FAN CONTROL
- Page15: INTERNAL TMDS LINK A/B
- Page16: INTERNAL TMDS LINK C/D
- Page17: MIOA, MIOB, NVPLL
- Page18: POWER SUPPLY (RT9218) for NVVDD,FBVDDQ
- Page19: Other Powers - A3V3, DDC_5, TMDSPLL, TMDSIO, FBVTT and 5V-3V3 POWER SEQUENCING

REV HISTORY

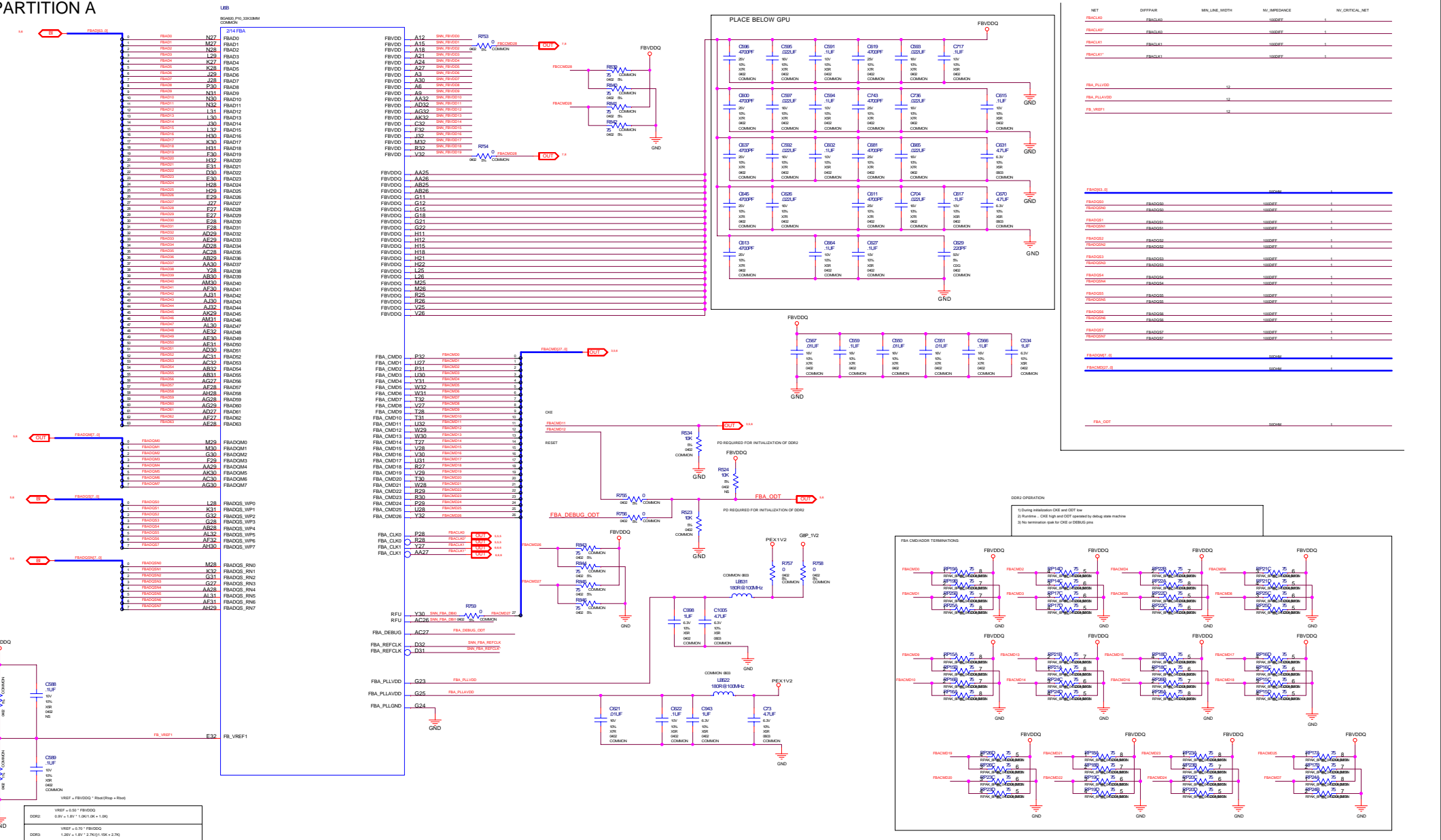
- A00
- 08/04/2005:
- 1.Page18: change power solution to RT9218 for NVVDD & FBVDDQ
- 10S
- 08/04/2005:
- 1.Page18: Move C913~C916 out form C910,C911 & Move C930,C931 out form C929
 - 2.Page19: Add C940 near C36
 - 3.Page19: Remove C16, C35, C55
- B00
- 12/06/2005:
- 1.ADD G73 circuit
- C00
- 04/26/2006:
- 1.Remove NV43 reserve circuit
 - 2.Page14: Add SPDIF circuit
 - 3.Page15: Add TMDS Dual_Link A/B
 - 4.Page17: Add MIOA Feature SLI CON
 - 5.Page18,19: Modify Power solution same as P345
- C01
- 06/26/2006:
- 1.Page18:Add MIOA SLI referenc power
 - 2.Page18:Add R0805 NVVDD to PEX1V2
 - 3.Page18:Add NVVDD Choke Footprint
 - 4.Page15/16:Add Bridge R for EMI
- A00
- 11/10/2006:V041-3.1 change model name to V088-0A
- 1.Page17:MIOA/B SLI signals reserve
 - 2.Page13:Straps reserve for G84
 - 3.Page10/11/12:Reserve DAC_VREF for G84 DAC
 - 4.Page3/4:Reserve FBIO ODT for G84 DDR2
 - 5.Page3/4:Reserve FBIO External VREF for G84
 - 6.Page3/4/5/6/7/8:Reserve FBIO Dual Rank Implementation for G84
 - 7.Page3/4/14:Reserve I/O changes for G84
 - 8.Page3/9/15/16/19:Reserve Power rail for G84

REV	VARIANT	NPVN	ASSEMBLY
0	BASE	80210295-BASE-SCM	BASE LEVEL GENERIC SCHEMATIC ONLY. COMMON & NO. STUFF ASSEMBLY NOTES AND BOM NOT FINAL
1	SKU00	80210295-0000-000	GF-6600-AD4 GEN 300267MHZ 256MB 84-FBGA DDR2 16MX16 VGA+DVI+HDTV
2	SKU01	80210295-0001-000	GF-6600-AD4 GEN 300267MHZ 128MB 84-FBGA DDR2 16MX16 VGA+DVI+HDTV
3	<UNDEFINED>	<UNDEFINED>	<UNDEFINED>
4	<UNDEFINED>	<UNDEFINED>	<UNDEFINED>
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8	<UNDEFINED>	<UNDEFINED>	<UNDEFINED>
9	<UNDEFINED>	<UNDEFINED>	<UNDEFINED>
10	<UNDEFINED>	<UNDEFINED>	<UNDEFINED>
11	<UNDEFINED>	<UNDEFINED>	<UNDEFINED>
12	<UNDEFINED>	<UNDEFINED>	<UNDEFINED>
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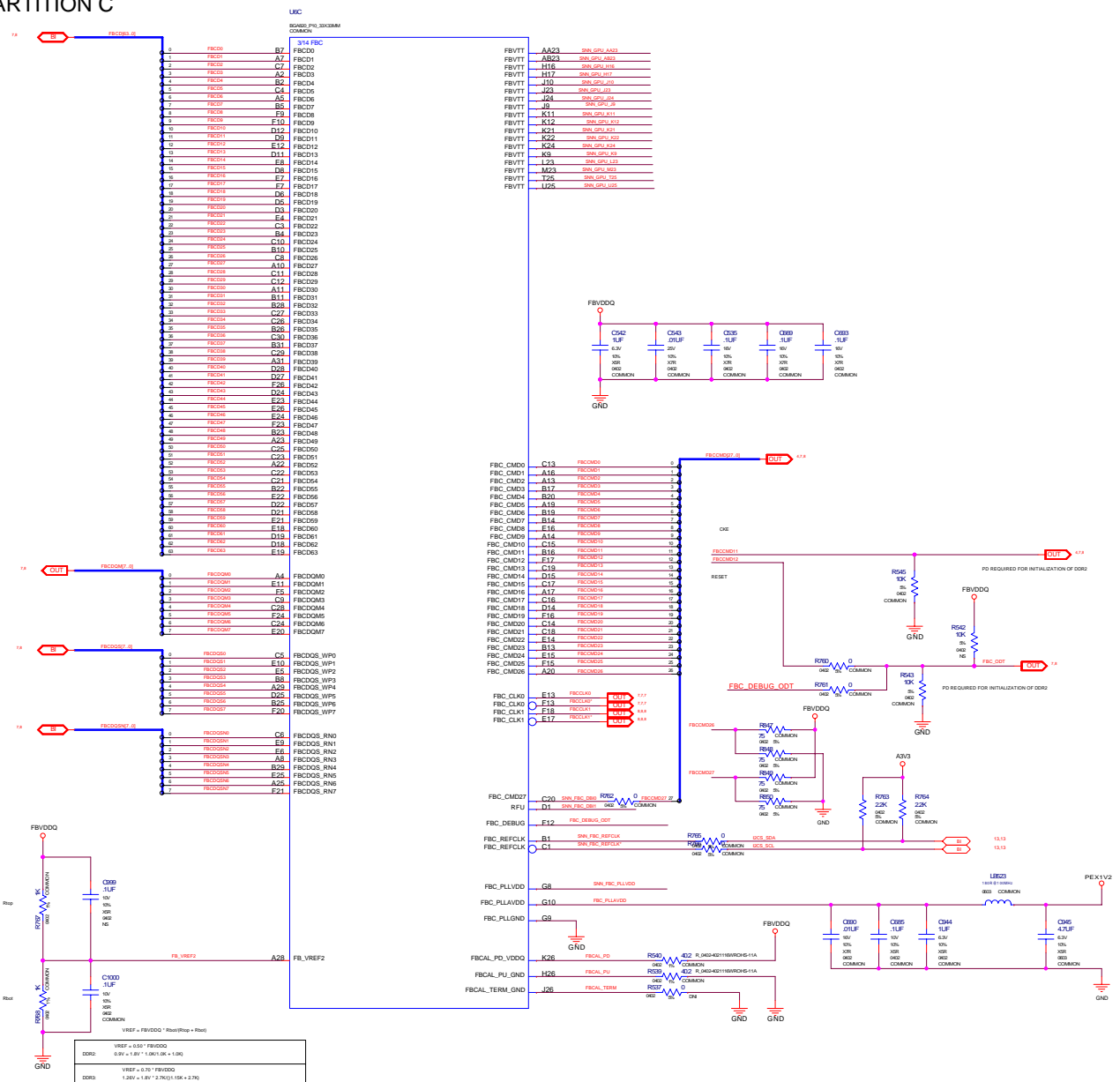
02 PCI EXPRESS, NVVDD, VDD33



FB PARTITION A



04 FB BANK C, FBVTT TERMINATIONS

[illegible][illegible]

FBCDQM7.0	500M	1
FBCDQM97.0	500M	1

FBC 007

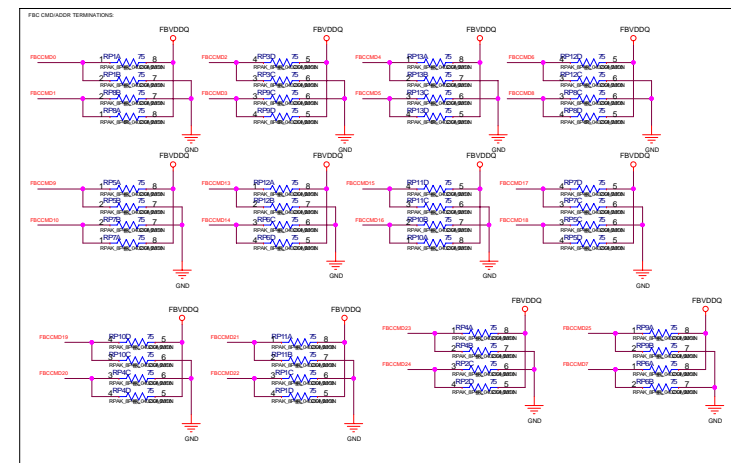
FBICAL_PO 12

FBICAL_PU	12
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Patrono, Denise	12
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DDR2 OPERATION

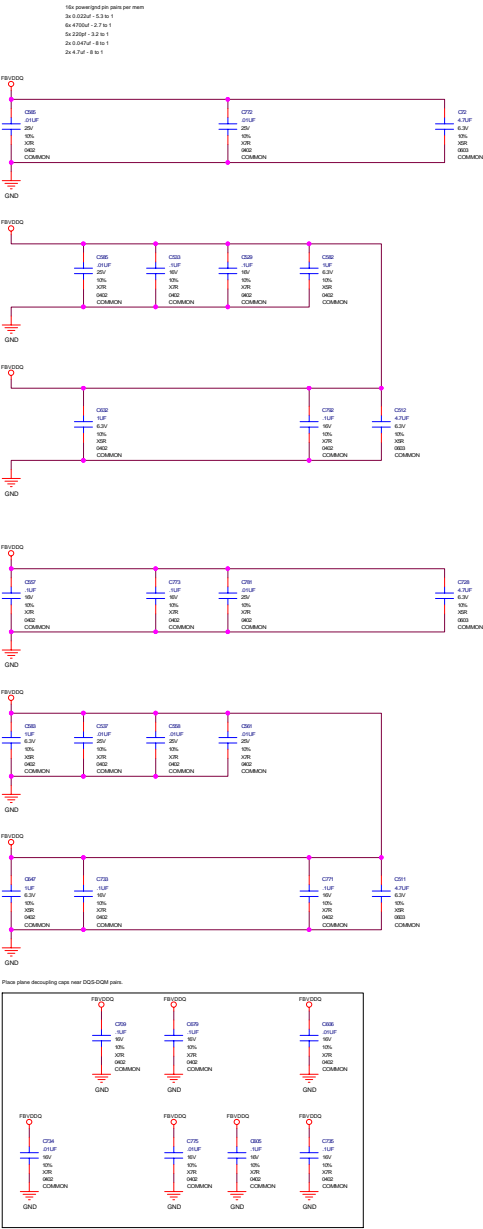
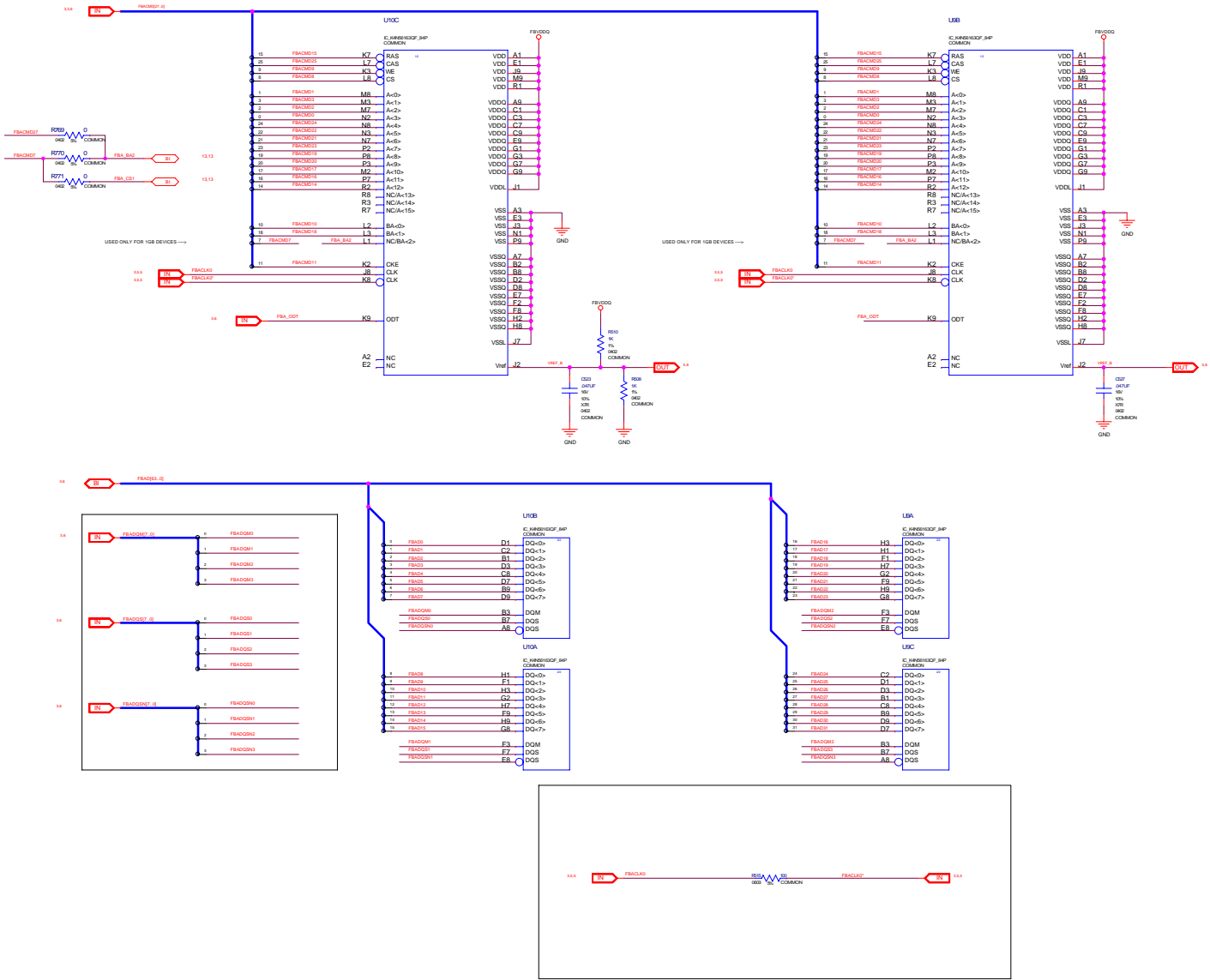
- 1) During initialization CKE and ODT low
- 2) Runtime - CKE high and ODT operated by debug state machine
- 3) No termination-spike for CKE or DEBUG pins



05 MEMORY PARTITION A 0.31

FBA MEMORY 1st bank 0.31

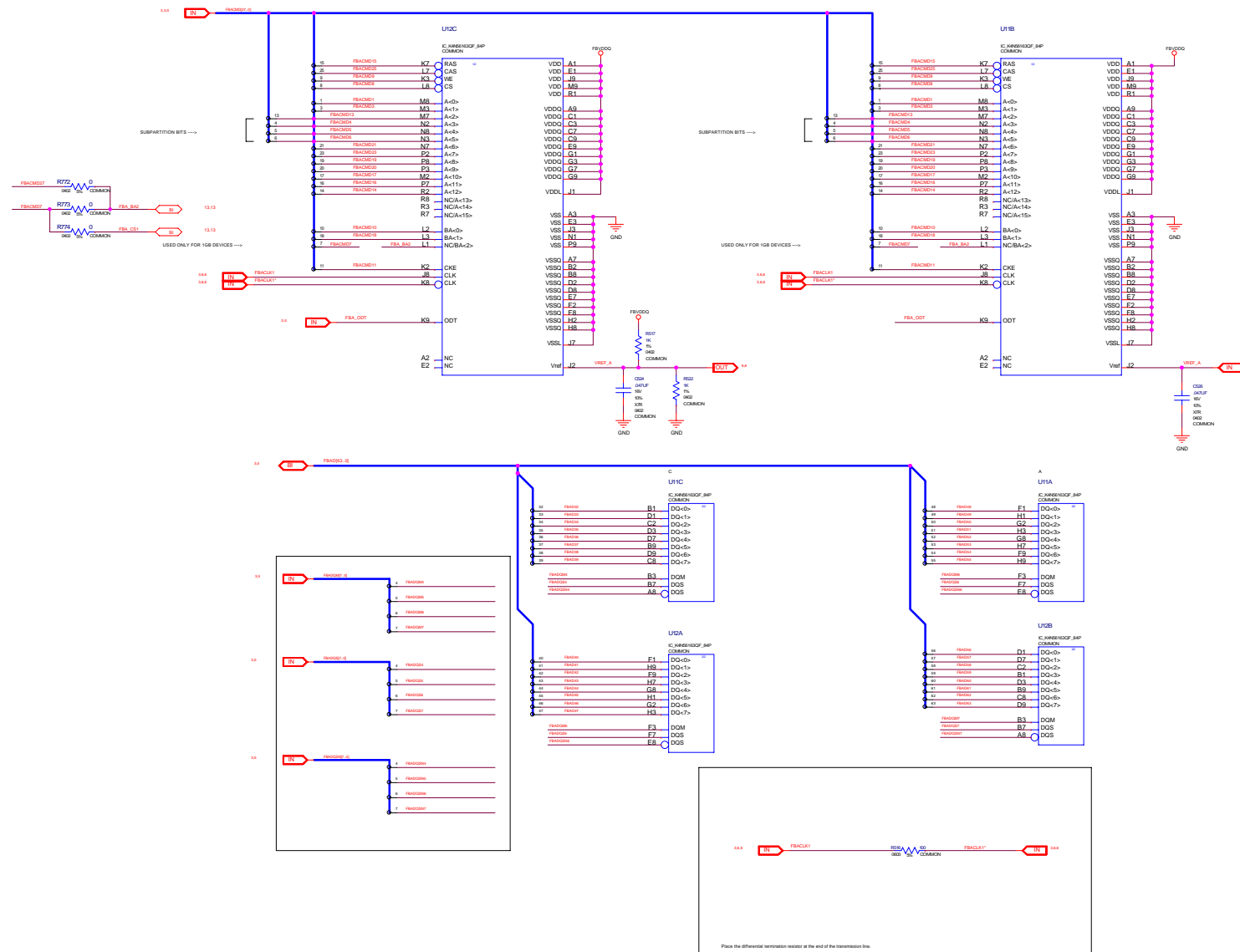
PLACE ALL DISCRETE COMPONENTS AS NEAR AS POSSIBLE TO MEMORY



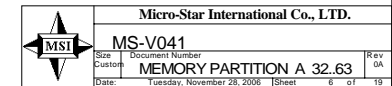
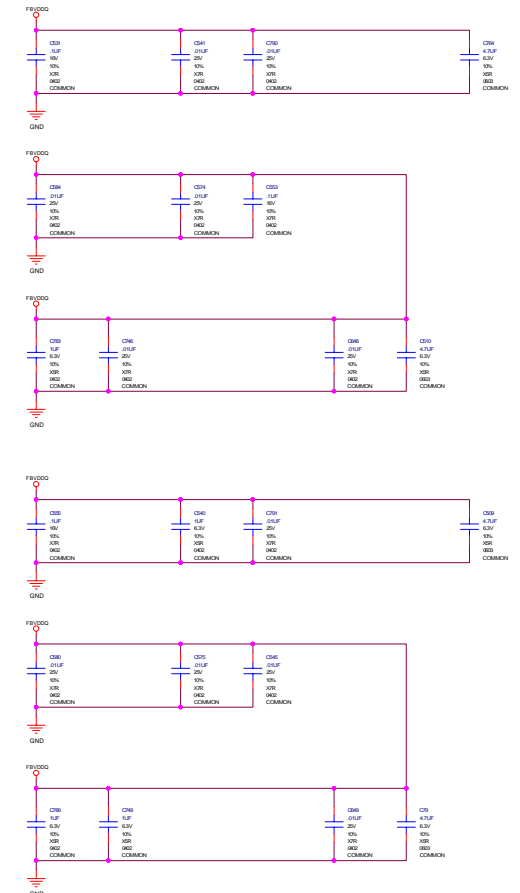
06 MEMORY PARTITION A 32..63

FBA MEMORY 1st bank 32..63

PLACE ALL DISCRETE COMPONENTS AS NEAR AS POSSIBLE TO MEMORY



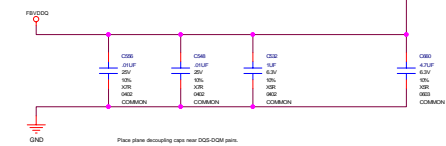
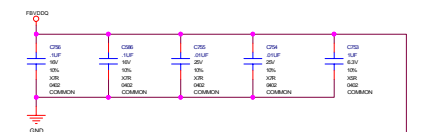
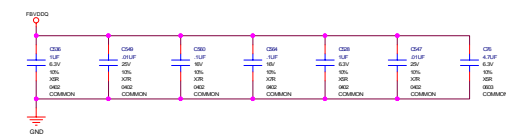
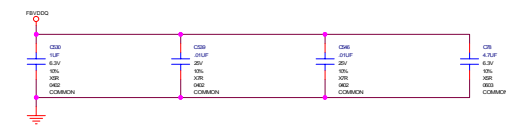
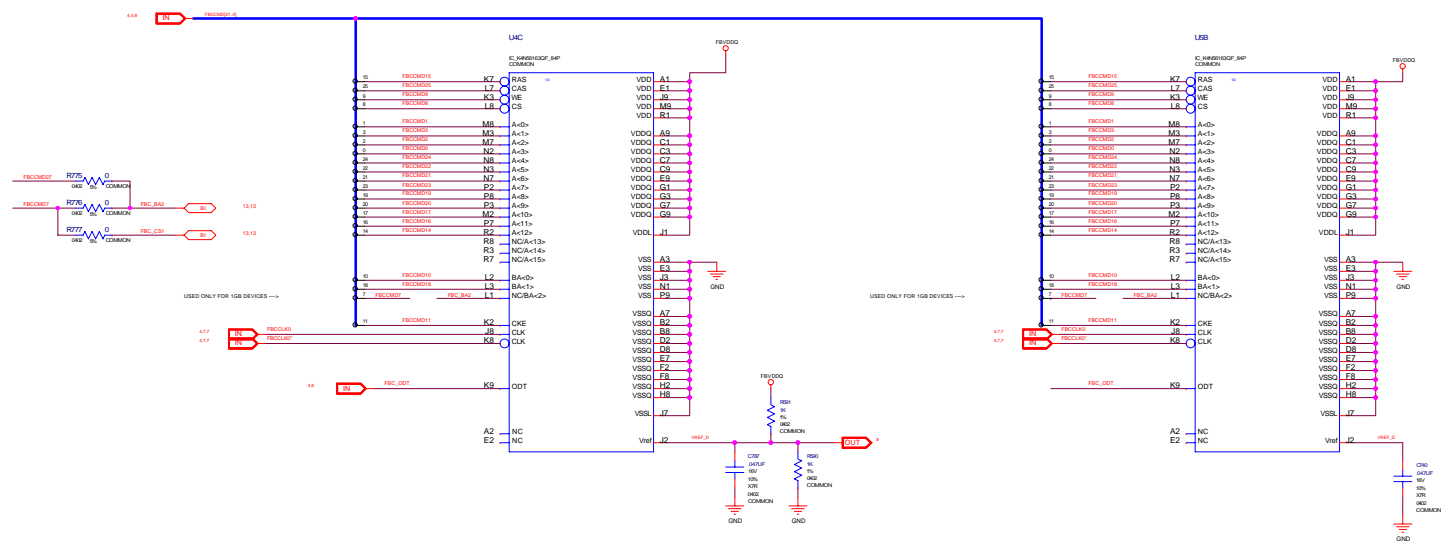
16x powerline pin pairs per mm
3x 0.022uF - 5.3 to 1
6x 4700uF - 2.7 to 1
5x 220pF - 3.2 to 1
2x 0.047uF - 8 to 1
2x 4.7uF - 8 to 1



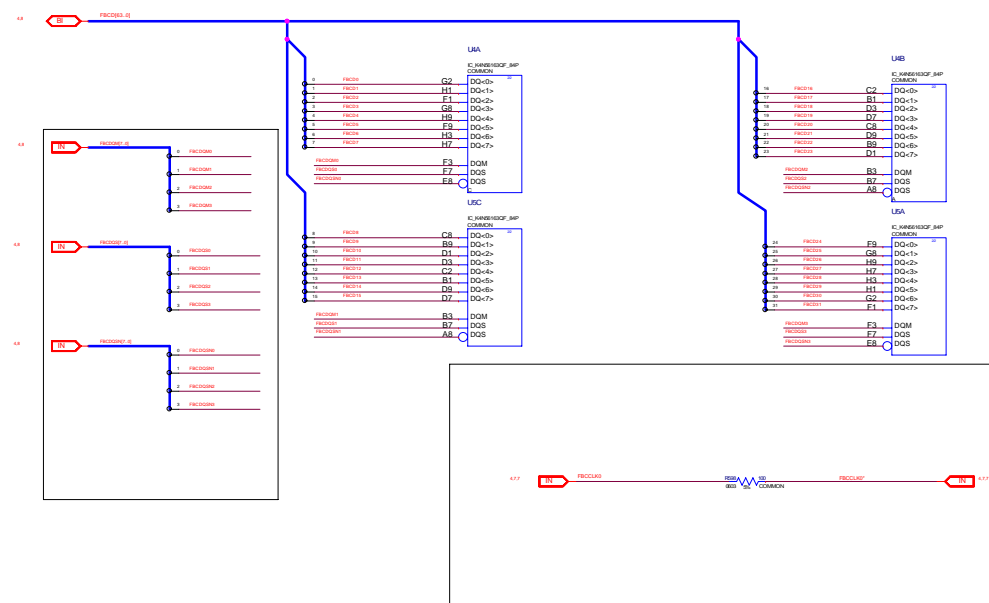
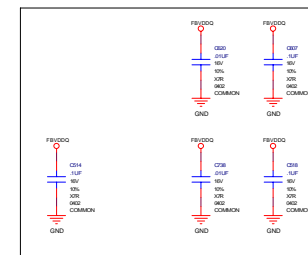
07 MEMORY PARTITION C 0..31

FBC MEMORY 2nd bank 0..31

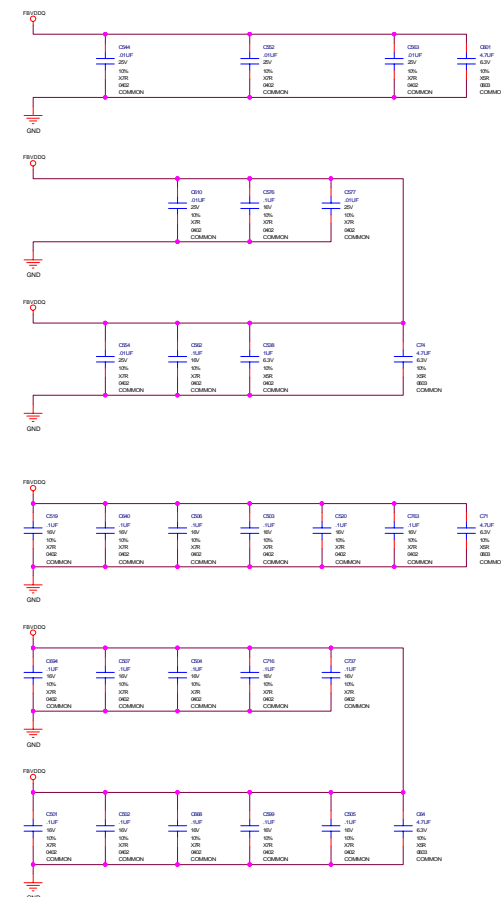
PLACE ALL DISCRETE COMPONENTS AS NEAR AS POSSIBLE TO MEMORY



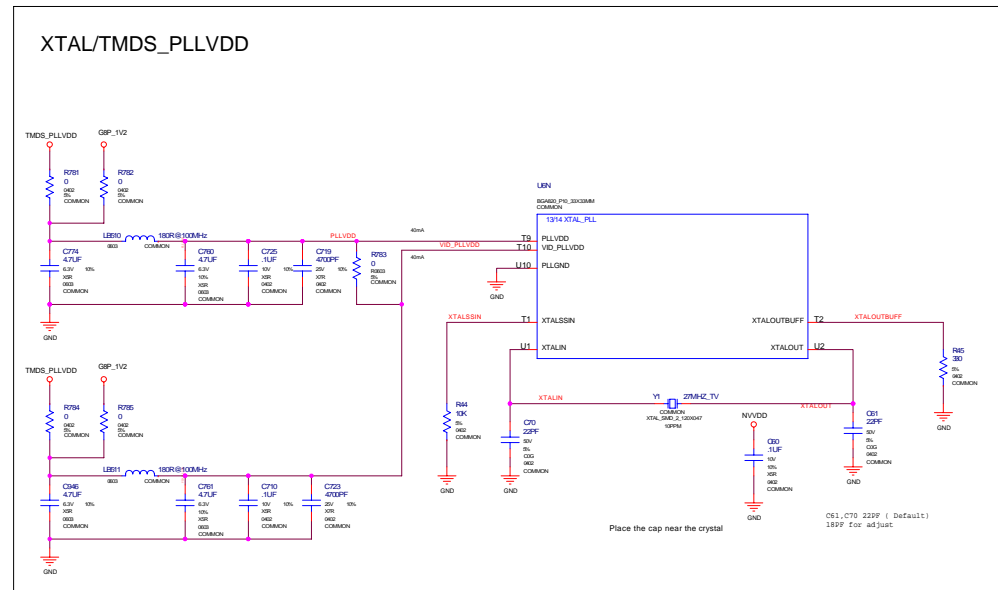
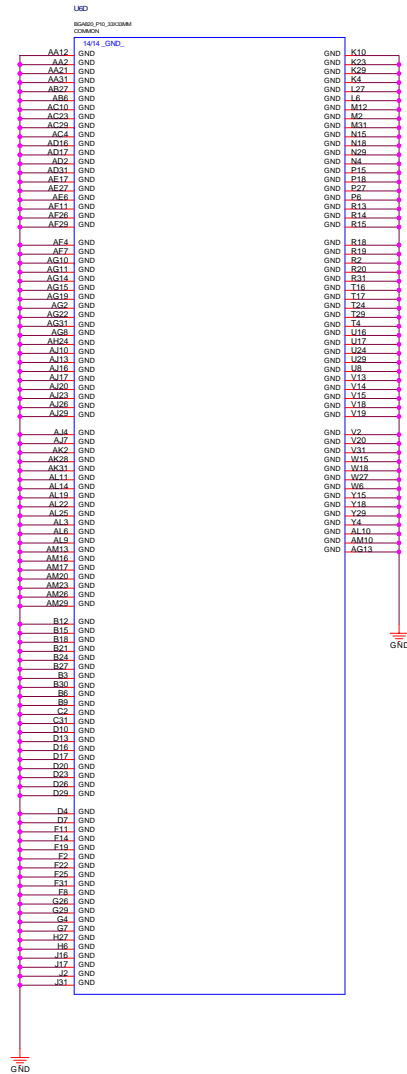
Place plane decoupling caps near DQS-DQM pairs



PLACE ALL DISCRETE COMPONENTS AS NEAR AS POSSIBLE TO MEMORY



09 GPU GND / TMDS_PLLVDD



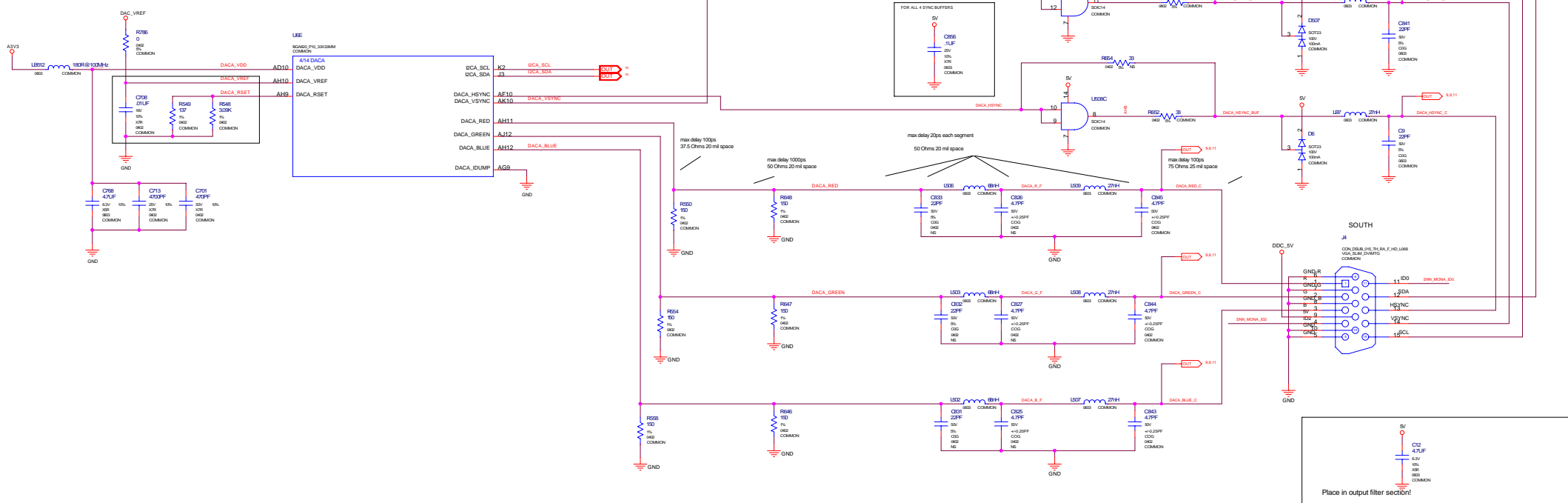
10 DACA - VGA

NET_NAME	MIN_LINE_WIDTH	SV_CRITICAL_NET	INV_IMPEDANCE
DACA_SCL			
DACA_BSDA			
DACA_MYSINC		2	500M
DACA_MYSINC_BSF		2	500M
DACA_MYSINC_BSF		2	500M
DACA_MYSINC_C		2	500M
DACA_MYSINC_C		2	500M
A1B		2	500M
A1B		2	500M
DACA_RED		1	500M
DACA_GREEN		1	500M
DACA_BLUE		1	500M
DACA_X_F		1	500M
DACA_X_F		1	500M
DACA_X_F		1	500M
DACA_RED_C		1	500M
DACA_GREEN_C		1	500M
DACA_BLUE_C		1	500M
DACA_VDD	12		
DACA_VREF	12		
DACA_RESET	12		

Note that this impedance is the highest one on the x-net for a 4-layer stackup.

Change for G73

C708 0.1u
R549 124ohm
R548 1.78Kohm



Micro-Star International Co., LTD.

MS-V041		
Size Custom	Document Number DACA - VGA	Rev 0A
Date: Monday, November 13, 2006	Sheet	10 of 19

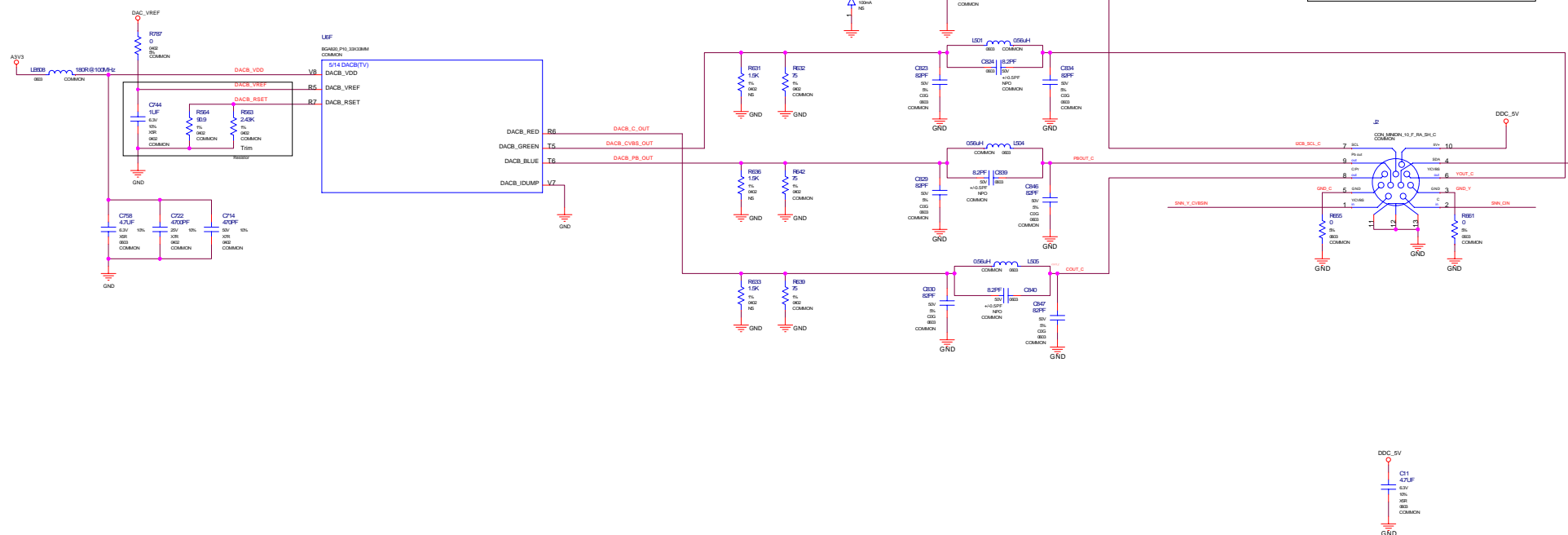
11 DACB - TVOUT, VIDEO IN

NET_NAME	MIN_LINE_WIDTH	NV_CRITICAL_NET	NV_REFERENCE
DACB_C_OUT		1	5000mil
DACB_VREF_INOT		1	5000mil
DACB_PN_OUT		1	5000mil
VOOUT_C		1	5000mil
VOOUT_C		1	5000mil
PNOUT_C		1	5000mil
DACB_VDD	12		
DACB_VREF	12		
DACB_VSET	12		
VVRESET	12		
QND_C	12		
QND_V	12		

Note that this is the highest impedance on the xnet

Change for G73

C744 0.1u
R564 124ohm
R563 1.78Kohm

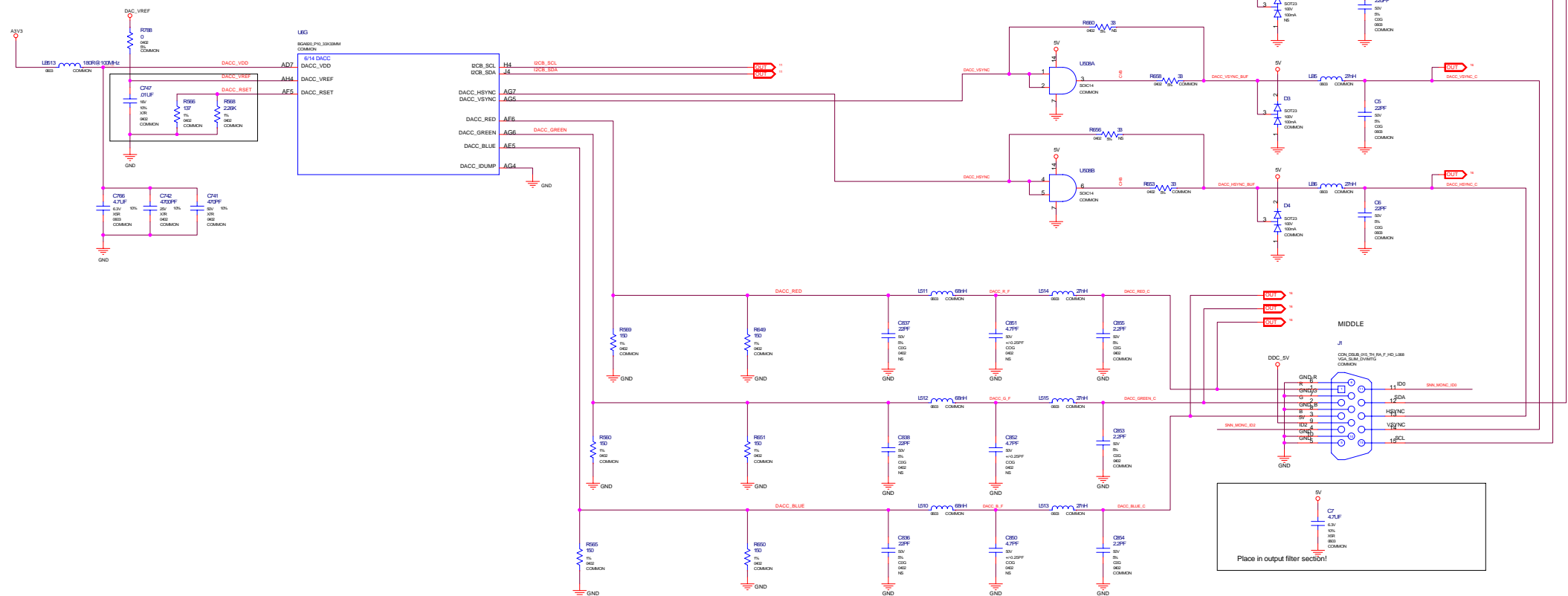


2 DACC - VGA

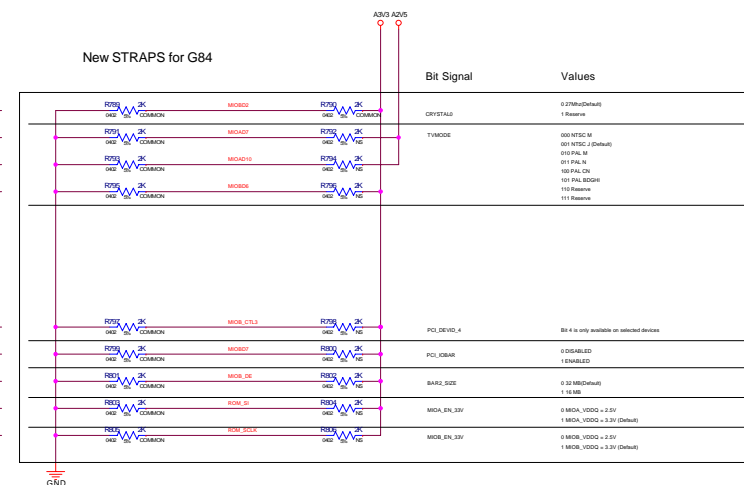
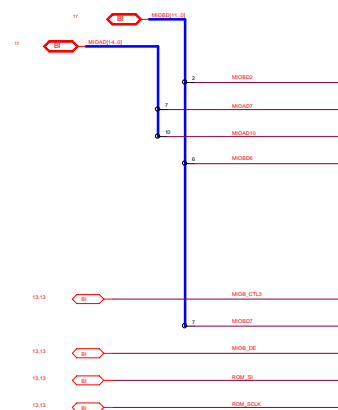
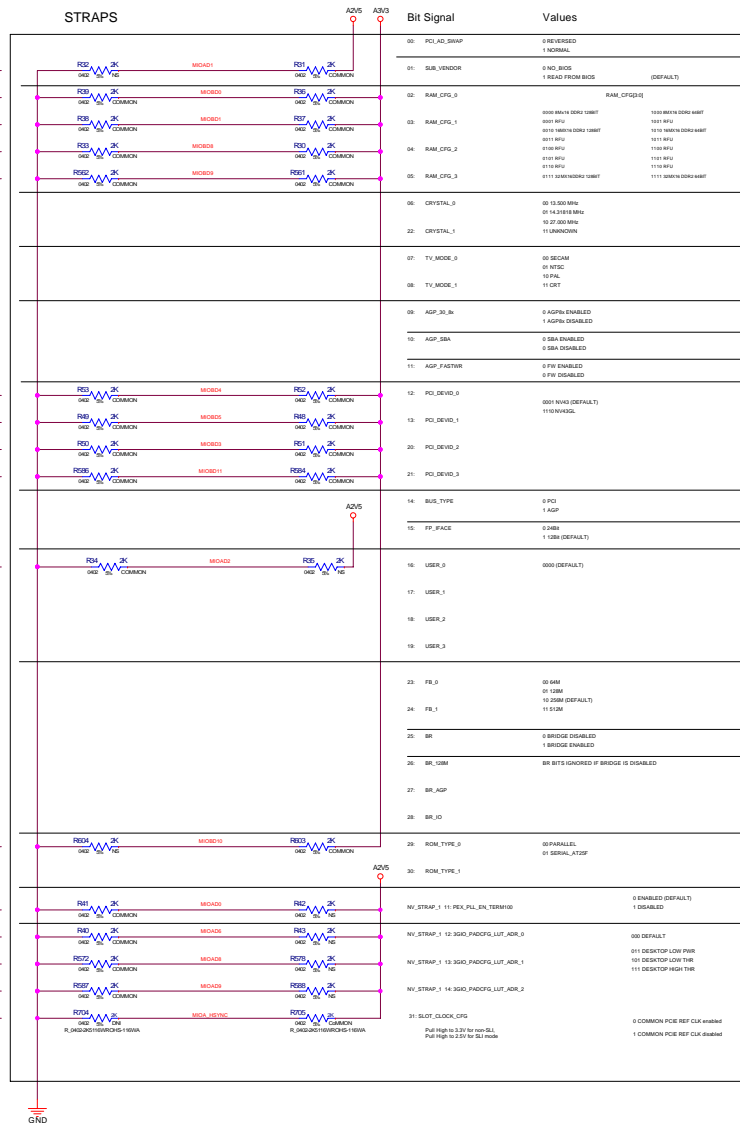
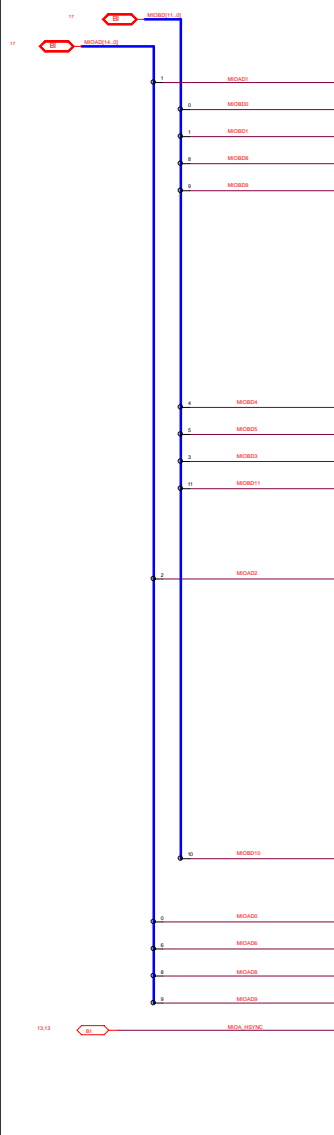
NET_NAME	MIN_WIDTH	NET_SPACING_RULE	NV_CRITICAL_NET	NV_APPEARANCE
DOE_SCL				
DOE_BNA				
DACC_HSYNC		2	NOCRN	
DACC_VSYNC		2	NOCRN	
DACC_HSYNC_BUF		2	NOCRN	
DACC_VSYNC_BUF		2	NOCRN	
DACC_HSYNC_C		2	NOCRN	
DACC_VSYNC_C		2	NOCRN	
CHE		2	NOCRN	
LVIS		2	NOCRN	
DACC_RED		1	NOCRN	
DACC_GREEN		1	NOCRN	
DACC_BLUE		1	NOCRN	
DACC_X_F		1	NOCRN	
DACC_X_F		1	NOCRN	
DACC_X_F		1	NOCRN	
DACC_RED_F		1	NOCRN	
DACC_GREEN_F		1	NOCRN	
DACC_BLUE_F		1	NOCRN	
DACC_VDD	18			
MMIOCS1PST	32			
MMIOCS1SET	32			

Change for G73

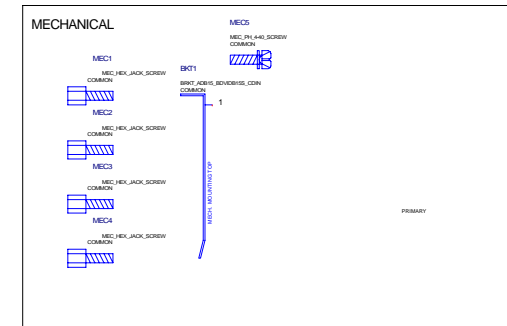
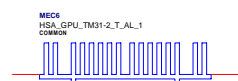
C747 0.1u
R566 124ohm
R568 1.78Kohm



13 STRAPS, FANSINK, MECHANICALS (Strap R using 2K if no specail required)

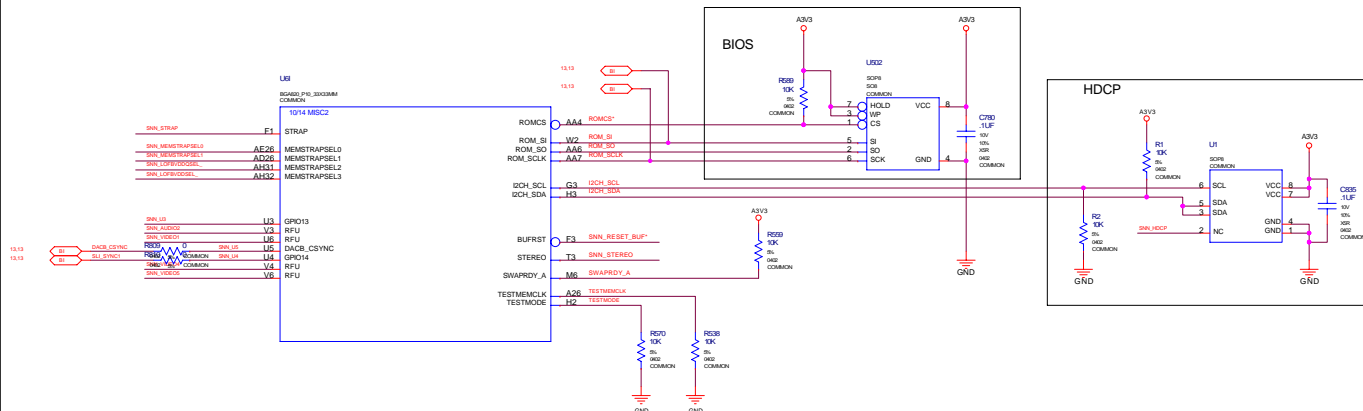
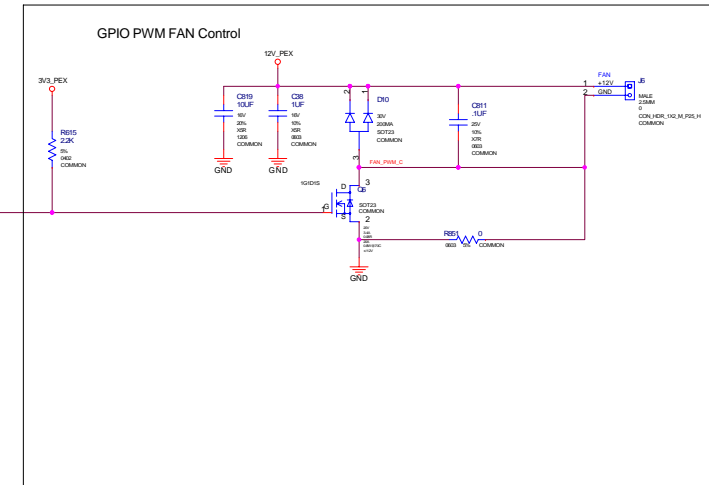
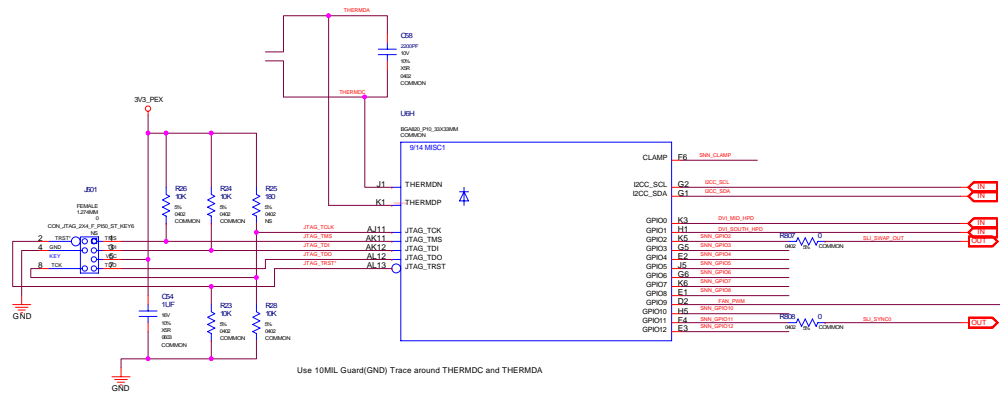
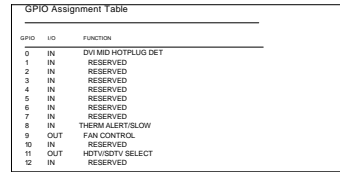


Reserve by PCB placement only



14 GPIO, HDCP, VBIOS, FAN CON

JTAG, GPIO, BIOS ROM

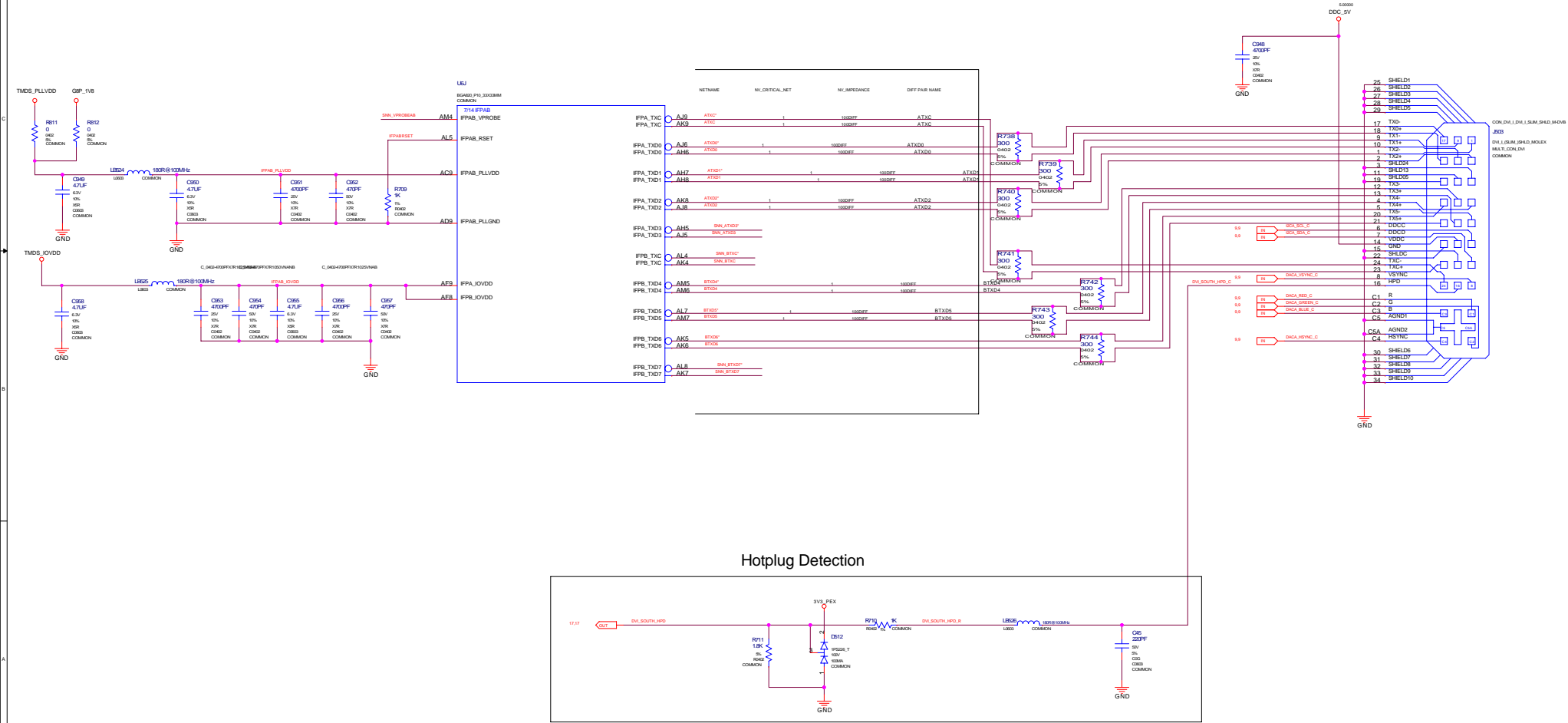


15 INTERNAL TMD5 LINK A/B

IFPAB NET RULES

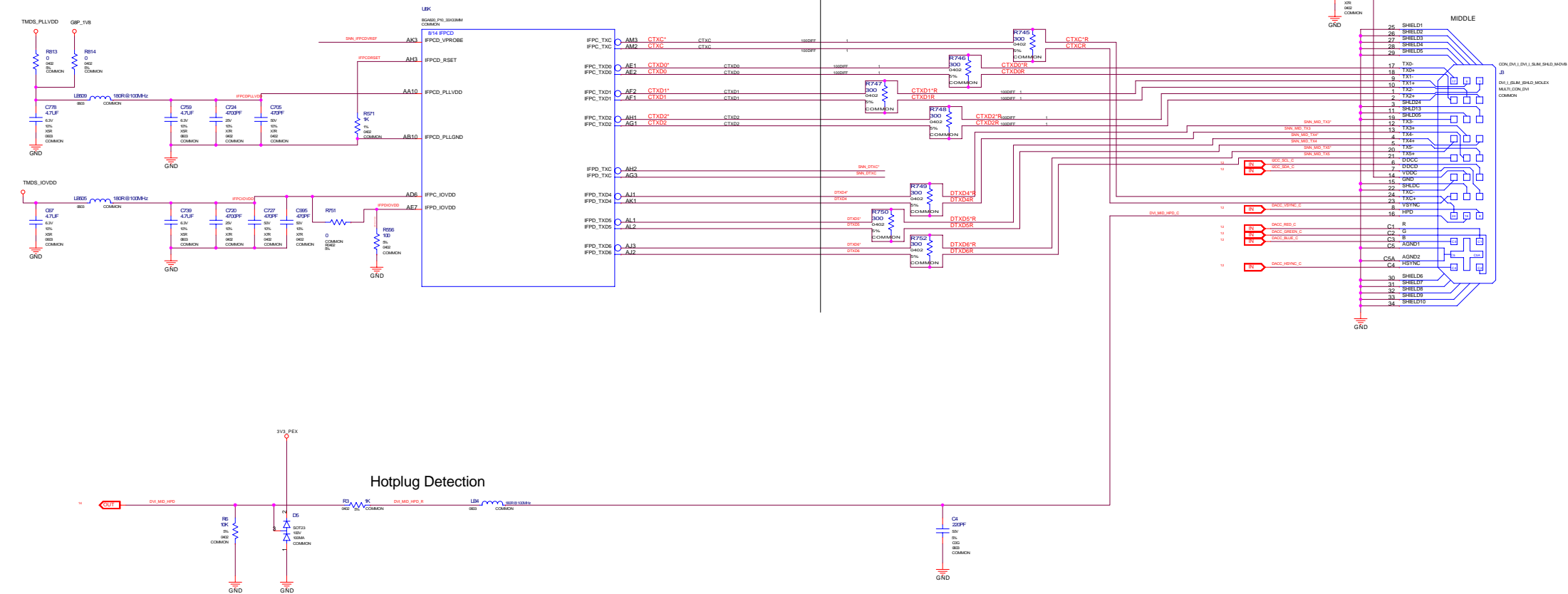
NET	W, CRITICAL	W, IMPEDANCE	DIFF PAIR
IFPAB, RSET	1	50OHM	
DVI_SOUTH_HPD_C	1	50OHM	
DVI_SOUTH_HPD_A	1	50OHM	

NET	VOLTAGE	MAX, CURRENT	MIN, WIDTH
IFPAB, PLLVDD	1.5000V	0.04	16.0
IFPAB, PLLVDD	1.5000V	0.04	16.0



16 INTERNAL TMDS LINK C/D

NET	MIN_LINE_WIDTH	VOLTAGE
#PCDREF	12	3.3V
#PCDPLVDD	12	3.3V
#PCDQVDD	12	3.3V
#PCDKVDD	12	3.3V
#PCDQSET	12	

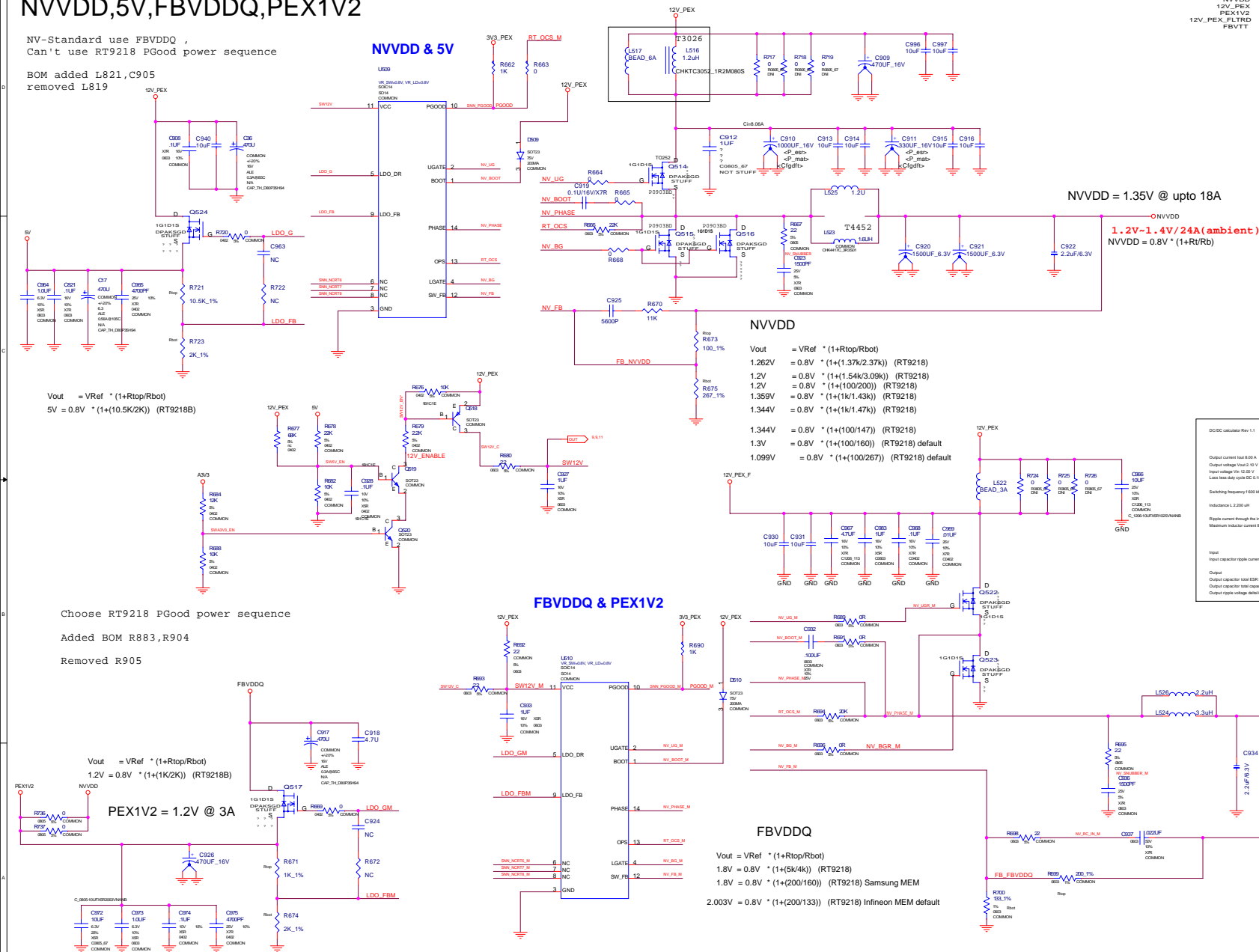


18 Power Supply (RT9218)

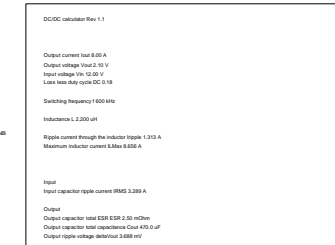
NVVDD,5V,FBVDDQ,PEX1V2

NV-Standard use FBVDDQ ,
Can't use RT9218 PGood power sequence

BOM added L821,C905
removed L819



Net Name	MIN	LINE_WIDTH	VOLTAGE
SV	16	3	3V
RVVDD	16	20	1.35V
12V_PEX	20	6	12V
PEX1V2	20	6	1.2V
12V_PEX_FLTRD	20	6	12V
FBVT1	20	1.5	FBVT12 V
DRIVE3_1V2	20		
UGATE_1	20		
UGATE_1	20		
UGATE_2	20		
UGATE_2	20		
NODE_1	20		
NODE_2	20		
12V_F8	10		
1B12V_VDD	10		
COMP1_NVDD	10		
FB1_NVDD	10		
COMP2_5V	10		
FB2_5V	10		
FB1_1V2	10		
REFTR_5V	10		
1B1_REFOUT	10		
VREF_3V3	10		
FB3_RC	10		
BOOST_1	20		
BOOST_2	20		
FREQ_SE1	10		
SE_NVDD	10		
SE_5V	10		
SE_1V2	10		
UGATE_1_RC	20		
UGATE_2_RC	20		
COMP1_RC	10		
COMP2_RC	10		
1VDD0_RC	10		
5V_RC	10		
NODE_1_S1UB	20		
NODE_2_S1UB	20		
CLGATE_1	20		
BOOST	20		
SVBOOST	20		



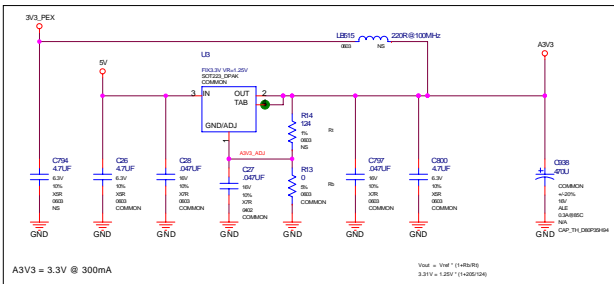
FBVDDQ = 1.8V @ upto 5A

1.8V/5.0A

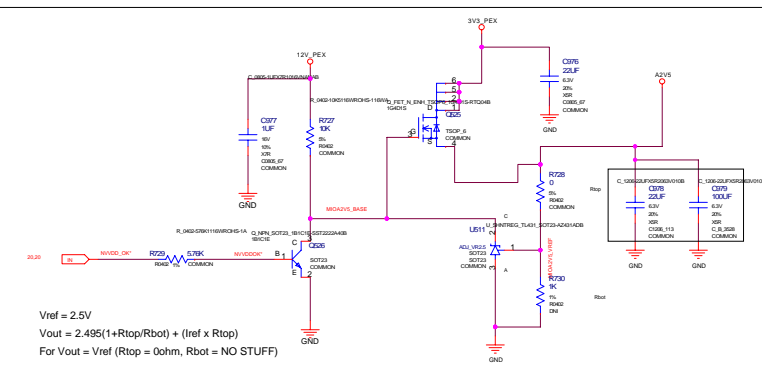

$$V_{out} = V_{Ref} * (1 + R_{top}/R_{bot})$$
$$1.8V = 0.8V * (1 + (5k/4k)) \quad (RT9218)$$
$$1.8V = 0.8V * (1 + (200/160)) \quad (RT9218) \text{ Samsung MEM}$$
$$2.003V = 0.8V * (1 + (200/133)) \quad (RT9218) \text{ Infineon MEM default}$$

A3V3,A2V5,TMDS_PLLVDD,TMDS_IOVDD

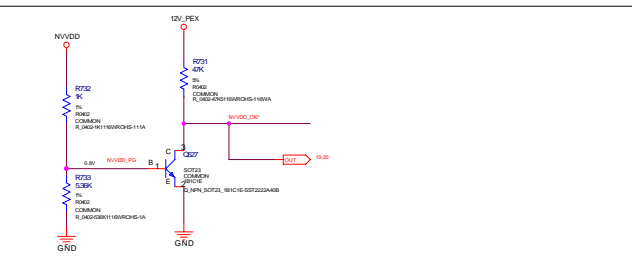
A3V3



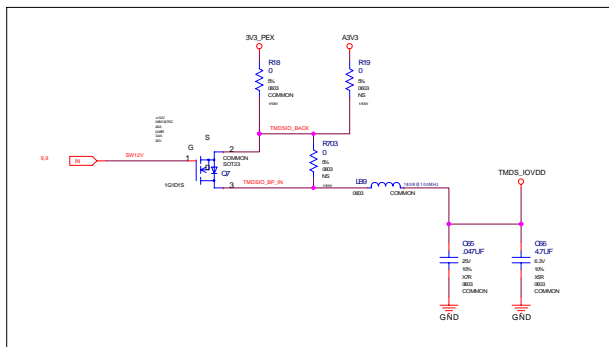
A2V5



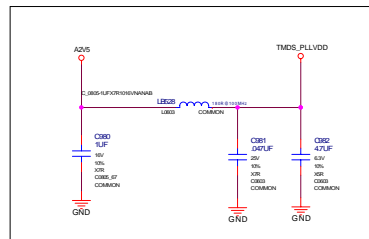
Power Sequencing for FBVDDQ & A2V5



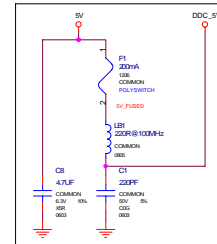
TMDS IO SUPPLY WITH BACKDRIVE PROTECTION



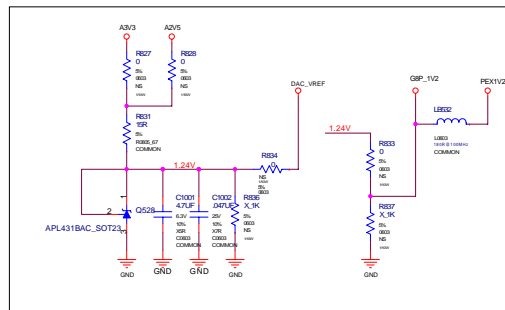
TMDS PLL Supply



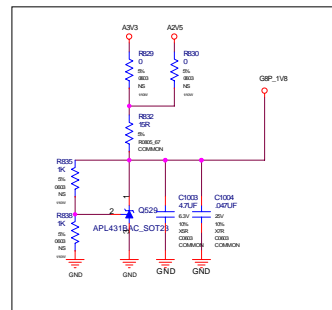
DDC 5V



DAC_VREF & 1V2



1V8

[illegible]